

細節
刻度 10:1

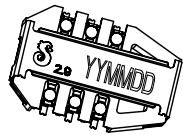
RECOMMENDED PCB LAYOUT
SCALE: 4/1 (TOL: ±0.05mm)

REV.	ECN NO.	OR DESCRIPTION	REVISED	DATE
B	ECN NO. T070182		AMY	2007.06.14
C	ECN T080204 無錫晶圓廠新		R.YIJIAN	2008.12.20
D	ECN. NO C100063		ARES	2010.03.11

- SPECIFICATIONS:**
- VOLTAGE RATING : 30VDC / CONTACT.
 - CURRENT RATING : 0.5A / CONTACT.
 - JACK SHALL WITHSTAND 500V AC VOLTS BETWEEN ANY ADJACENT TERMINAL FOR 1 MINUTE.
 - JACK SHALL WITHSTAND 10000 CYCLES OF INSERTION AND WITHDRAWAL WITH MATE PLUG OR GAUGE PLUG AFTER TESTING CONTACT RESISTANCE SHALL NOT EXCEED 0.1 OHMS.
 - NORMAL FORCE
 - INITIAL: 50g Min.
 - AFTER LIFE TEST: 50g Min.
 - MEASURING CONDITIONS:
 - TEMPERATURE: FROM -40°C TO +85°C.
 - RELATIVE HUMIDITY: FROM -40% TO +85%
 - RESISTANCE TO SOLDERING HEAT: 260°C 10 secs.
 - PACKING: TAPE & REEL.
 - COPPLANARITY: 0.1mm Max.
 - DURABILITY: MATED 10000 CYCLES WITHOUT DEGRADING ELECTRICAL CHARACTERISTICS.
 - TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
 - HALOGEN FREE PRODUCT IDENTIFICATION MARK ON JACK:
 - HALOGEN FREE PRODUCT IDENTIFICATION LABEL ON PACKAGING:
 - FOR LEAD-FREE PROCESS.

PART NO.
2SM1001-01X111

- PACKAGE I: TAPE & REEL
- BODY COLOR I: BLACK
- CONTACT PLATING I: Gold flash; Contact area Au 30u" min. DIM-A (HIGHT)
- 3: 2.9mm



C	LATCH	1	COPPER ALLOY 0.15T	Mat: 50 Min. W: 20u" min.
B	CONTACT	6	COPPER ALLOY 0.1T	Contact area Au 30u" min. Gold flash, 20u" min.
A	BODY	1	HI-TEMP. THERMOPLASTIC	Gold flash, 20u" min. W: 1.5mm min.
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
UNLESS OTHERWISE SPECIFIED TOLERANCES				
DECIMALS: ANGLES:				
X	:±0.5	X	:±2°	
X.X	:±0.3	X.X	:±1°	
X.XX	:±0.2			
TITLE: SIM CARD CONN.				
Singatron Enterprise Co., Ltd. 信登企業股份有限公司				
DWN	ARES	2010.03.11	PART NO. 2SM1001-013111	
CHKD	MUYUAN	2010.03.11	SCALE: 4/1	UNIT: mm
APVD	ROBIN	2010.03.11	SIZE: A3	SHEET: 1 OF 1
REV: D				
CUSTOMER COPY				